



30V N+P Dual Channel MOSFETs

General Description

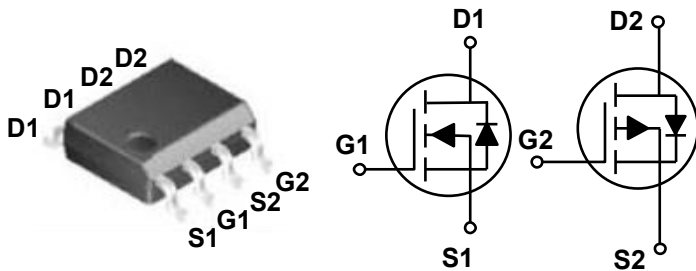
These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)}$	I_D
30 V	21 mΩ	7 A
-30 V	35 mΩ	-6 A

Features

- Fast Switching
- Green Device Available

SOP-8 Pin Configuration



Applications

- DC Fan
- Inverter
- Synchronous Buck

Absolute Maximum Ratings $T_A=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Rating		Units
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
I_D	Drain Current - Continuous	7	-6	A
I_{DM}	Drain Current - Pulsed (NOTE 1)	30	-30	A
P_D	Power Dissipation	2		W
T_J	Operating Junction Temperature Range	-55 to 150		$^{\circ}C$
T_{STG}	Storage Temperature Range	-55 to 150		$^{\circ}C$
Marking Code		BC021 , 3047EM		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	62.5	$^{\circ}C/W$

**30V N+P Dual Channel MOSFETs****N Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =30V, V _{GS} =0V, T _J =25°C	---	---	1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =6A	---	---	21	mΩ
		V _{GS} =4.5V, I _D =5A	---	---	31	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	---	3.0	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =5A	---	4.6	---	S

Dynamic and Switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} =24V, V _{GS} =4.5V, I _D =7A	---	10	---	nC
Q _{gs}	Gate-Source Charge		---	2	---	
Q _{gd}	Gate-Drain Charge		---	6	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =15V, V _{GS} =10V, R _{GEN} =3.3Ω, I _D =1A	---	8	---	nS
T _r	Rise Time		---	7	---	
T _{d(off)}	Turn-Off Delay Time		---	20	---	
T _f	Fall Time		---	6	---	
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, F=1MHz	---	1700	---	pF
C _{oss}	Output Capacitance		---	380	---	
C _{rss}	Reverse Transfer Capacitance		---	260	---	

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current		---	---	4.3	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A	---	---	1	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.



30V N+P Dual Channel MOSFETs

Characteristics Curves

FIG. 1-Drain Current

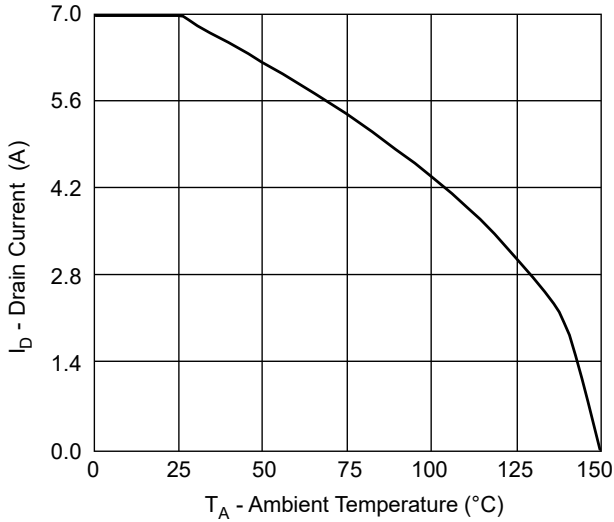


FIG. 2-Normalized $V_{GS(th)}$ vs T_J

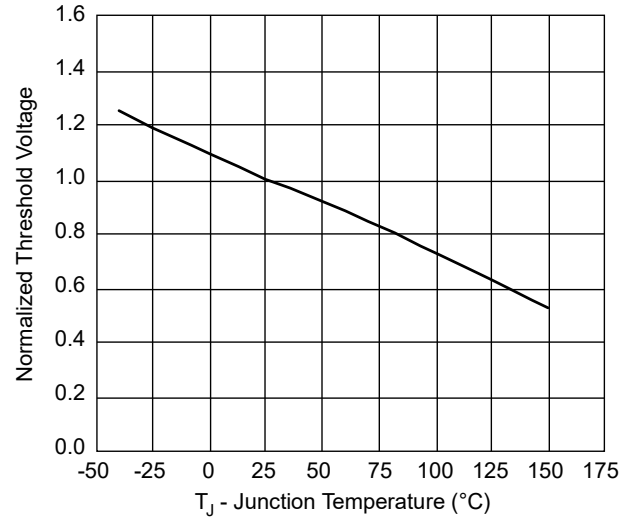


FIG. 2-Normalized $R_{DS(on)}$ vs T_J

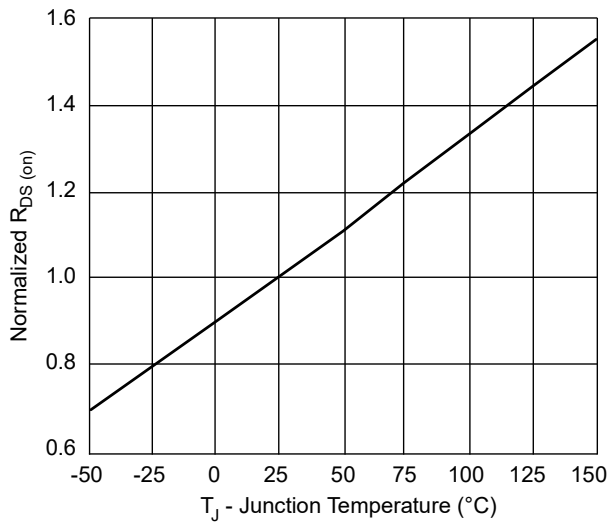


FIG. 4-Transfer Characteristics

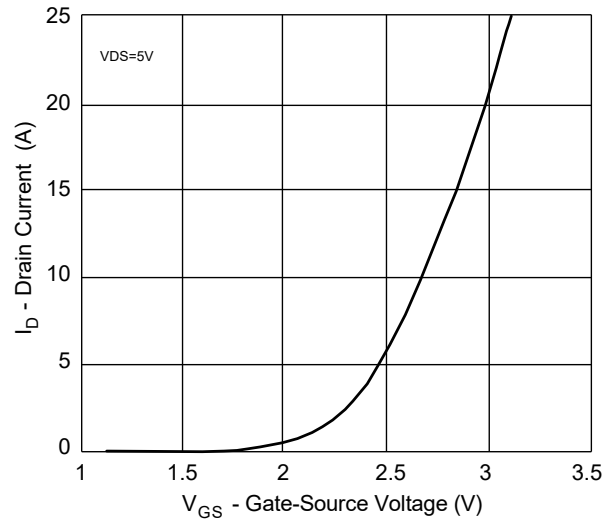
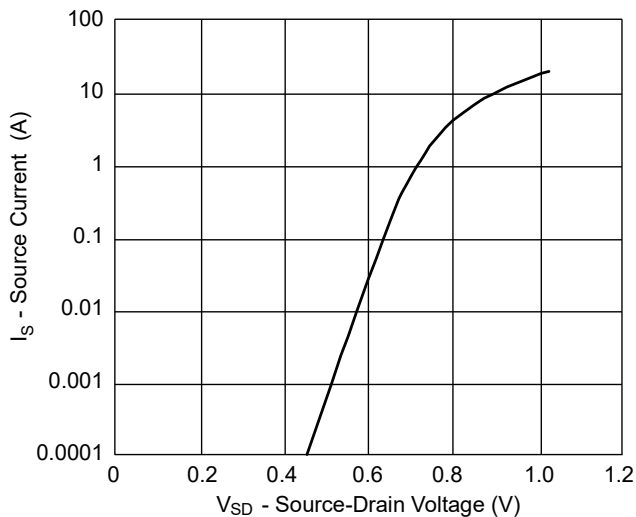


FIG. 5-Forward Characteristics



**30V N+P Dual Channel MOSFETs****P Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V , I _D = -250uA	-30	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} = -30V , V _{GS} = 0V	---	---	-1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±20V , V _{DS} = 0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = -10V , I _D = -5A	---	---	35	mΩ
		V _{GS} = -4.5V , I _D = -4A	---	---	55	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D = -250uA	-1.0	---	-3.0	V
gfs	Forward Transconductance	V _{DS} = -10V , I _D = -5A	---	4.9	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} = -24V , V _{GS} = -4.5V , I _D = -6A	---	9	---	nC
Q _{gs}	Gate-Source Charge		---	2	---	
Q _{gd}	Gate-Drain Charge		---	6	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} = -15V , V _{GS} = -10V , R _{GEN} = 3.3Ω , I _D = -1A	---	10	---	nS
T _r	Rise Time		---	8	---	
T _{d(off)}	Turn-Off Delay Time		---	25	---	
T _f	Fall Time		---	13	---	
C _{iss}	Input Capacitance	V _{DS} = -10V , V _{GS} = 0V , F= 1MHz	---	970	---	pF
C _{oss}	Output Capacitance		---	370	---	
C _{rss}	Reverse Transfer Capacitance		---	180	---	

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current		---	---	-2.6	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S = -2.6A	---	---	-1.3	V

NOTES :

- The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
- Essentially independent of operating temperature.



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Characteristics Curves

FIG. 6-Drain Current

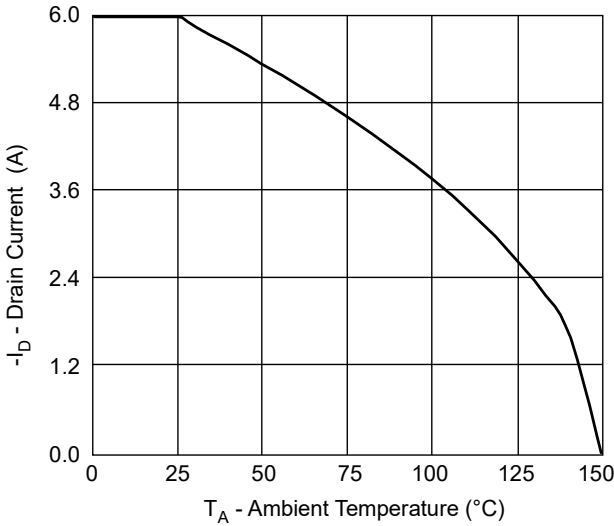


FIG. 7-Normalized V_{GS(th)} vs T_J

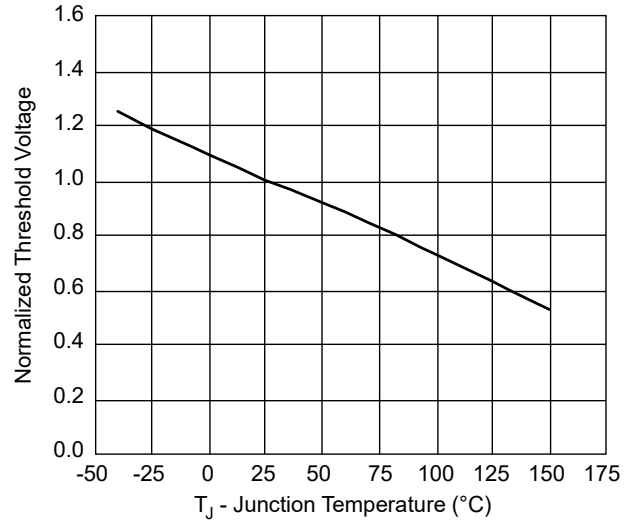


FIG. 8-Normalized R_{DS(on)} vs T_J

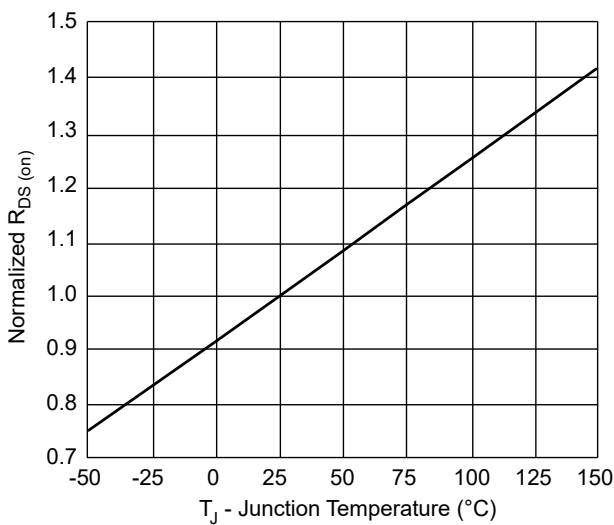


FIG. 9-Transfer Characteristics

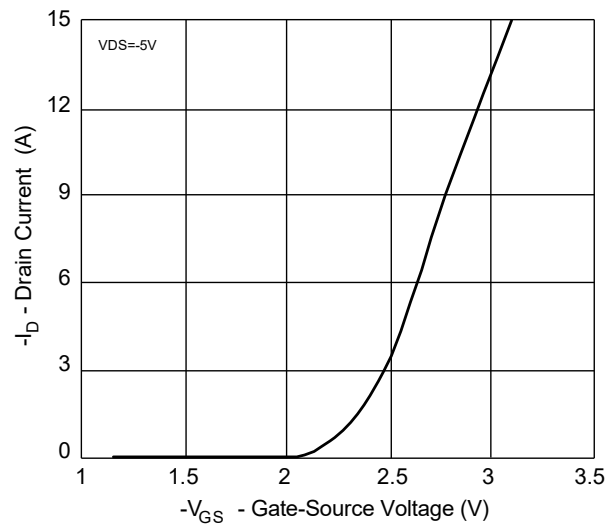
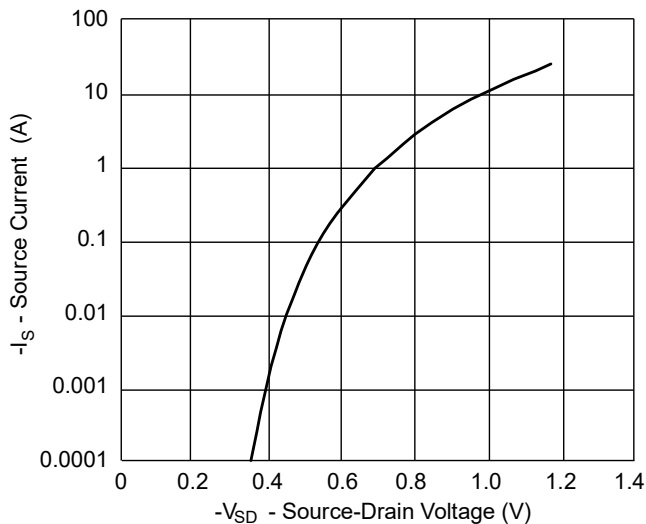


FIG. 10-Forward Characteristics



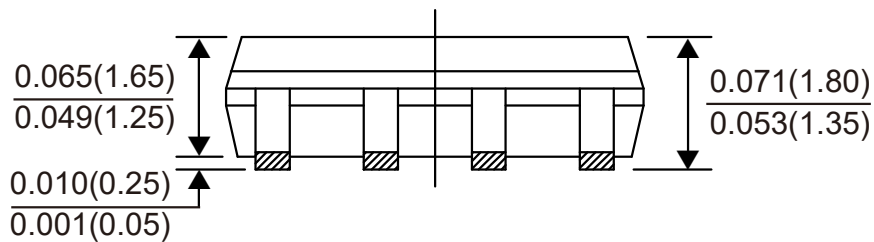
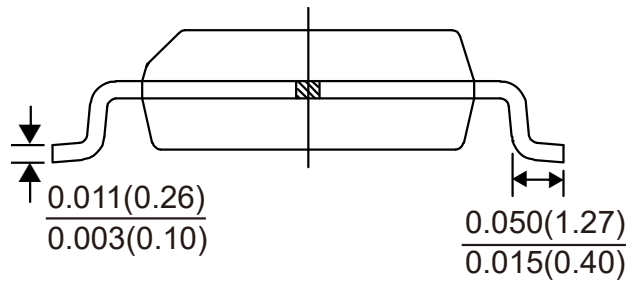
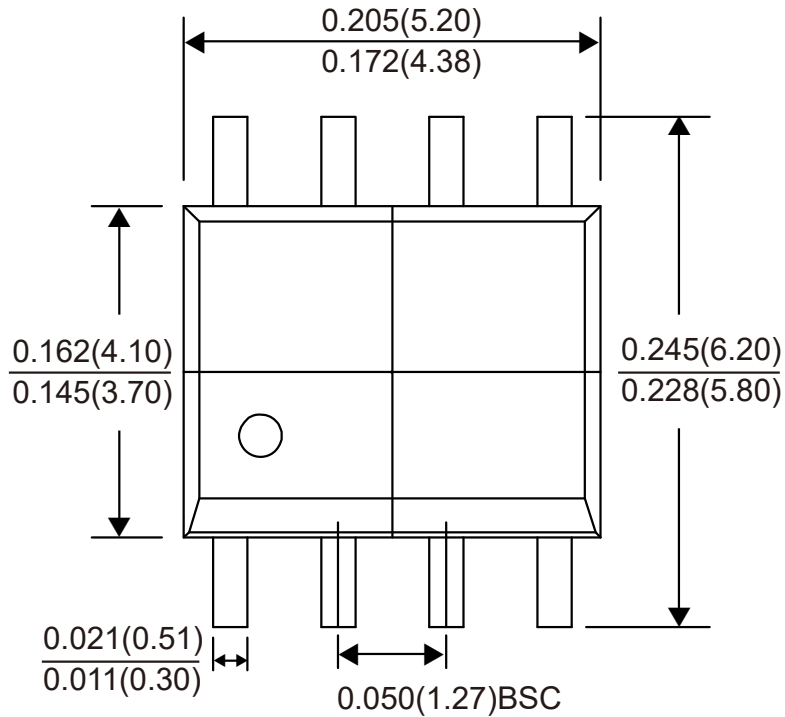


S8MBC021



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Package Outline Dimensions



SOP-8

Dimensions in inches and (millimeters)



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